Standard Products UT80C196KD Microcontroller

Datasheet



September 2002

FEATURES

- 20MHz 16-bit Microcontroller compatible with Industry Standard's MCS-96 ISA
 - Register to Register Architecture - 1000 Byte Register RAM
- □ Three 8-bit I/O Ports
- On-board Interrupt Controller
- □ Three Pulse-Width Modulated Outputs
- □ High Speed I/O
- UART Serial Port
- Dedicated Baud Rate Generator
- Software and Hardware Timers
 16-Bit Watchdog Timer, Four 16-Bit Software Timers
 Three 16-Bit Counter/Timers
- Error detection and correction for external memory accesses
- **QML** Q compliant part
- □ Standard Microcircuit Drawing 5962-98583

INTRODUCTION

The UT80C196KD is compatible with industry standard's MCS-96 instruction set. The UT80C196KD is supported by commercial hardware and software development tools.

The UT80C196KD accesses instruction code and data via a 16-bit address and data bus. The 16-bit bus allows the microcontroller to access 128K bytes of instruction/data memory. Integrated software and hardware timers, high speed I/O, pulse width modulation circuitry, and UART make the UT80C196KD ideal for control type applications. The CPU's ALU supports byte and word adds and subtracts, 8 and 16 bit multiplies, 32/16 and 16/8 bit divides, as well as increment, decrement, negate, compare, and logical operations. The UT80C196KD's interrupt controller prioritizes and vectors 18 interrupt events. Interrupts include normal interrupts and special interrupts. To reduce power consumption, the microcontroller supports software invoked idle and power down modes.

The UT80C196KD is packaged in a 68-lead quad flatpack.

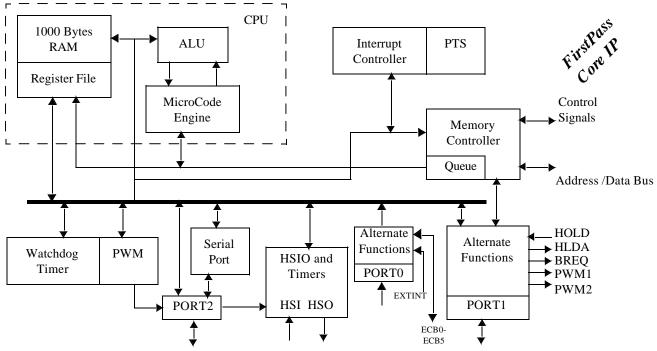


Figure 1. UT80C196KD Microcontroller

1.0 SIGNAL DESCRIPTION

Port 0 (P0.0 - P0.7): Port 0 is an 8-bit input only port when used in its default mode. When configured for their alternate function, five of the bits are bi-directional EDAC check bits as shown in Table 1.

Port 1 (P1.0 - P1.7): Port 1 is an 8-bit, quasi-bidirectional, I/O port. All pins are quasi-bidirectional unless the alternate function is selected per Table 2. When the pins are configured for their alternate functions, they act as standard I/O, not quasi-bidirectional.

Port 2 (P2.0 - P2.7): Port 2 is an 8-bit, multifunctional, I/O port. These pins are shared with timer 2 functions, serial data I/O and PWM0 output, per Table 3.

AD0-AD7: The lower 8-bits of the multiplexed address/data bus. The pins on this port are bidirectional during the data phase of the bus cycle.

AD8-AD15: The upper 8-bits of the multiplexed address/data bus. The pins on this port are bidirectional during the data phase of the 16-bit bus cycle. When running in 8-bit bus width, these pins are non-multiplexed, dedicated upper address bit outputs.

HSI: Inputs to the High Speed Input Unit. Four HSI pins are available: HSI.0, HSI.1, HSI.2, and HSI.3. Two of these pins (HSI.2 and HSI.3) are shared with the HSO Unit. Two of these pins (HSI.0 and HSI.1) have alternate functions for Timer 2.

HSO: Outputs from the High Speed Output Unit. Six HSO pins are available: HSO.0, HSO.1, HSO.2, HSO.3, HSO.4, and HSO.5. Pins HSO.4 and HSO.5 are shared with pins HSI.2 and HSI.3 of the HSI Unit respectively.

Table 1. Port 0 Alternate Functions			
Port Pin	Alternate Name	Alternate Function	
P0.0-P0.3, P0.6	ECB0-ECB4	Error Detection & Correction Check Bits	
P0.4 P0.5		Input Port Pins	
P0.7	EXTINT	Setting IOC1.1=1 will allow P0.7 to be used for EXTINT (INT07)	

	Table 2. Port 1 Alternate Functions			
Port Pin	Alternate Name	Alternate Function		
P1.0	P1.0	I/O Pin		
P1.1	P1.1	I/O Pin		
P1.2	P1.2	I/O Pin		
P1.3	PWM1	Setting IOC3.2=1 enables P1.3 as the Pulse Width Modulator (PWM1) output pin.		
P1.4	PWM2	Setting IOC3.3=1 enables P1.4 as the Pulse Width Modulator (PWM2) output pin.		
P1.5	BREQ	Bus Request, output activated when the bus controller has a pending external memory cycle.		
P1.6	HLDA	Bus Hold Acknowledge, output indicating the release of the bus.		
P1.7	HOLD	Bus Hold, input requesting control of the bus.		

Table 3. Port 2 Alternate Functions

Port Pin	Alternate Name	Alternate Function
P2.0	TXD	Transmit Serial Data.
P2.1	RXD	Receive Serial Data.
P2.2	EXTINT	External interrupt. Clearing IOC1.1 will allow P2.2 to be used for EXTINT (INT07)
P2.3	T2CLK	Timer 2 clock input and Serial port baud rate generator input.
P2.4	T2RST	Timer 2 Reset
P2.5	PWM0	Pulse Width Modulator output 0
P2.6	T2UP-DN	Controls the direction of the Timer 2 counter. Logic High equals count down. Logic low equals count up.
P2.7	T2CAPTURE	A rising edge on P2.7 causes the value of Timer 2 to be captured into this register, and generates a Timer 2 Capture interrupt (INT11).

1.1 Hardware Interface

1.1.1 Interfacing with External Memory

The UT80C196KD can interface with a variety of external memory devices. It supports either a fixed 8-bit bus width or a dynamic 8-bit/16-bit bus width, internal READY control for slow external memory devices, a bus-hold protocol that enables external devices to take over the bus, and several bus-control modes. These features provide a great deal of flexibility when interfacing with external memory devices.

1.1.1.1 Chip Configuration Register

The Chip Configuration Register (CCR) is used to initialize the UT80C196KD immediately after reset. The CCR is fetched from external address 2018H (Chip Configuration Byte) after removal of the reset signal. The Chip Configuration Byte (CCB) is read as either an 8-bit or 16-bit word depending on the value of the BUSWIDTH pin. The composition of the bits in the CCR are shown in Table 4.

	Table 4. Chip Configuration Register	
Bit	Function	
7	N/A	
6	N/A	
5	IRC1 - Internal READY Mode Control	
4	IRC0 - Internal READY Mode Control	
3	Address Valid Strobe Select (ALE/ADV)	
2	Write Strobe Mode Select (WR and BHE/WRL and WRH)	
1	Dynamic Bus Width Enable	
0	Enable Power Down Mode	

There are 8 configuration bits available in the CCR. However, bits 7 and 6 are not used by the UT80C196KD. Bits 5 and 4 comprise the READY mode control which define internal limits for waitstates generated by the READY pin. Bit 3 controls the definition of the ALE/ADV pin for system memory controls while bit 2 selects between the different write modes. Bit 1 selects whether the UT80C196KD will use a dynamic 16-bit bus or whether it will be locked in as an 8-bit bus. Finally, Bit 0 enables the Power Down mode and allows the user to disable this mode for protection against inadvertent power downs.

1.1.1.2 Bus Width and Memory Configurations

The UT80C196KD external bus can operate as either an 8-bit or 16-bit multiplexed address/data bus (see figure 2). The value of bit 1 in the CCR determines the bus operation. A logic low value on CCR.1 locks the bus controller in 8-bit bus mode. If, however, CCR.1 is a logic high, then the BUSWIDTH signal is used to decide the width of the bus. The bus is 16 bits wide when the BUSWIDTH signal is high, and is 8 bits when the BUSWIDTH signal is low.

1.1.2 Reset

To reset the UT80C196KD, hold the $\overrightarrow{\text{RESET}}$ pin low for at least 16 state times after the power supply is within tolerance and the oscillator has stabilized. Resets following the power-up reset may be asserted for at least one state time, and the device will turn on a pull-down transistor for 16 state times. This enables the RESET signal to function as the system reset. The reset state of the external I/O is shown in Table 9, and the register reset values are shown in Table 8.

1.1.3 Instruction Set

The instruction set for the UT80C196KD is compatible with the industry standard MCS-96 instruction set used on the 80C196KD.

Table 5. Memory Map			
Memory Description	Begin	End	
External Memory ¹	02080H	0FFFFH	
Reserved	0205EH	0207FH	
PTS Vectors	02040H	0205DH	
Upper Interrupt Vectors	02030H	0203FH	
Reserved	02020H	0202FH	
Reserved	02019H	0201FH	
Chip Configuration Byte	02018H	02018H	
Reserved	02014H	02017H	
Lower Interrupt Vectors	02000H	02013H	
External Memory	00400H	1FFFH	
Internal Memory (RAM)	0001AH	003FFH	
Special Function Registers	00000H	00019H	

Notes:

1. The first instruction read following reset will be from location 2080h. All other external memory can be used as instruction and/or data memory.

Number	Interrupt Vector	Source(s)	Interrupt Vector Location	PTS Vector Location	Priority ¹ (0 is the Lowest Priority)
Special	Unimplemented Opcode	Unimplemented Opcode	2012h	N/A	N/A
Special	Software Trap	Software Trap	2010h	N/A	N/A
INT 15	NMI ²	NMI	203Eh	N/A	15
INT 14	HSI FIFO Full	HSI FIFO Full	203Ch	205Ch	14
INT 13	EXTINT 1 ²	Port 2.2	203Ah	205Ah	13
INT 12	Timer 2 Overflow	Timer 2 Overflow	2038h	2058h	12
INT 11	Timer 2 Capture ²	Timer 2 Capture	2036h	2056h	11
INT 10	HSI FIFO 4	HSI FIFO Fourth Entry	2034h	2054h	10
INT 9	Receive	RI Flag ³	2032h	2052h	9
INT 8	Transmit	TI Flag ³	2030h	2050h	8
INT 7	EXTINT ²	Port 2.2 or Port 0.7	200Eh	204Eh	7
INT 6	Serial Port	RI Flag and TI Flag ⁴	200Ch	204Ch	6
INT 5	Software Timer	Software Timer 0-3 Timer 2 Reset	200Ah	204Ah	5
INT 4	HSI.0 ²	HSI.0 Pin	2008h	2048h	4
INT 3	High Speed Outputs	Events on HSO.0 thru HSO.5 Lines	2006h	2046h	3
INT 2	HSI Data Available	HSI FIFO Full or HSI Holding Reg. Loaded	2004h	2044h	2
INT 1	EDAC Bit Error	Single Bit Error Single Bit Error OVF Double Bit Error	2002h	2042h	1
INT 0	Timer Overflow	Timer 1 or Timer 2	2000h	2040h	0

Notes:

- 1. The Unimplemented Opcode and Software Trap interrupts are not prioritized. The Interrupt Controller immediately services these interrupts when they are asserted. NMI has the highest priority of all prioritized interrupts. Any PTS interrupt has priority over lower priority interrupts, and over all other maskable interrupts. The standard maskable interrupts are serviced according to their priority number with INTO has the lowest priority of all interrupts.
- 2. These interrupts can be configured to function as independant, external interrupts.
- 3. If the Serial interrupt is masked and the Receive and Transmit interrupts are enabled, the RI flag and TI flag generate separate Receive and Transmit interrupts.
- 4. If the Receive and Transmit interrupts are masked and the Serial interrupt is enabled, both RI flag and TI flag generate a Serial Port interrupt.

Table 7. SFR Memory Mapping					
Address	HWin 0 Read	HWin 0 Write	HWin 1	HWin 15 ¹	
019H	Stack Pntr (hi)	Stack Pntr (hi)	Stack Pntr (hi)	Stack Pntr (hi)	
018H	Stack Pntr (lo)	Stack Pntr (lo)	Stack Pntr (lo)	Stack Pntr (lo)	
017H	IOS2	PWM0_CTRL	PWM2_CTRL	***	
016H	IOS1	IOC1	PWM1_CTRL	***	
015H	IOS0	IOC0	EDAC-CS ²	***	
014H	WSR	WSR	WSR	WSR	
013H	INT_MASK1	INT_MASK1	INT_MASK1	INT_MASK1	
012H	INT_PEND1	INT_PEND1	INT_PEND1	INT_PEND1	
011H	SP_STAT	SP_CON	RESERVED	***	
010H	PORT 2	PORT 2	RESERVED	PSW ²	
00FH	PORT 1	PORT 1	Timer 3(hi) ²	RESERVED	
00EH	PORT 0	BAUD RATE	Timer 3(lo) ²	RESERVED	
00DH	Timer 2 (hi)	Timer 2 (hi)	WDT-SCALE ²	T2CAPTURE (hi)	
00CH	Timer 2 (lo)	Timer 2 (lo)	IOC3	T2CAPTURE (lo)	
00BH	Timer 1 (hi)	IOC2	INT_PRI(hi) ²	***	
00AH	Timer 1 (lo)	Watchdog	INT_PRI(lo) ²	***	
009H	INT_PEND	INT_PEND	INT_PEND	INT_PEND	
008H	INT_MASK	INT_MASK	INT_MASK	INT_MASK	
007H	SBUF (RX)	SBUF (TX)	PTSSRV (hi)	***	
006H	HSI_status	HSO_command	PTSSRV (lo)	***	
005H	HSI_time(hi)	HSO_time (hi)	PTSSEL (hi)	***	
004H	HSI_time (lo)	HSO_time (lo)	PTSSEL (lo)	***	
003H	RESERVED	HSI_mode	RESERVED	***	
002H	RESERVED	RESERVED	RESERVED	RESERVED	
001H	Zero_reg (hi)	Zero_reg (hi)	Zero-reg (hi)	Zero_reg (hi)	
000H	Zero_reg (lo)	Zero_reg (lo)	Zero_reg (lo)	Zero_reg (lo)	

Notes:

For some functions that share a register address in HWindow0, the opposite access type (read/write) is available in HWindow 15 if indicated by the three asterisks (***).
 These registers are not available in the industry standard 80C196KD. Therefore, industry standard development software will not recognize these mnemonics, and you will only be able to access them via their physical addresses.

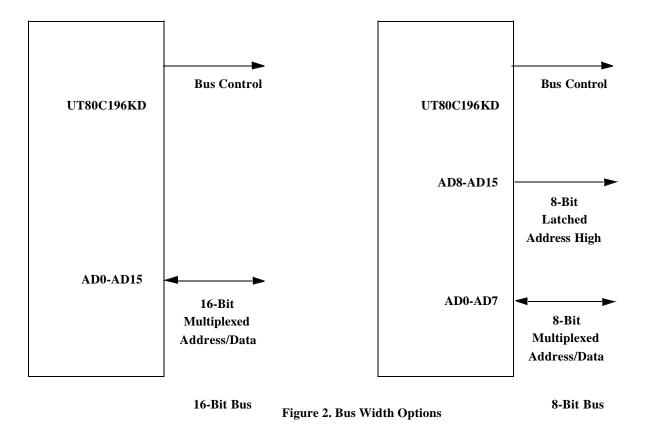
Table 8: Special Function Register Reset Values			
Internal Register	Binary Reset State	Hexadecimal Reset Value	
Stack Pointer (SP)	XXXX XXXX XXXX XXXX	XXXX	
I/O Status Register 2 (IOS2)	0000 0000	00	
I/O Status Register 1 (IOS1)	0000 0000	00	
I/O Status Register 0 (IOS0)	0000 0000	00	
Window Select Register (WSR)	0000 0000	00	
Interrupt Mask Register 1 (INT_MASK1)	0000 0000	00	
Interrupt Pending Register 1 (INT_PEND1)	0000 0000	00	
Serial Port Status Register (SP_STAT)	0000 1011	0B	
Port 2 Register (PORT2)	110X XXX1	XX	
Port 1 Register (PORT1)	1111 1111	FF	
Port 0 Register (PORT0)	XXXX XXXX	XX	
Timer 2 Value Register (TIMER2)	0000 0000 0000 0000	0000	
Timer 1 Value Register (TIMER1)	0000 0000 0000 0000	0000	
Interrupt Pending Register (INT_PEND)	0000 0000	00	
Interrupt Mask Register (INT_MASK)	0000 0000	00	
Receive Serial Port Register (SBUF (RX))	0000 0000	00	
HSI Status Register (HSI_status)	X0X0 X0X0	XX	
HSI Time Register (HSI_time)	XXXX XXXX XXXX XXXX	XXXX	
Zero Register (ZERO_REG)	0000 0000 0000 0000	0000	
PWM0 Control Register (PWM0_CTRL)	0000 0000	00	
I/O Control Register 1 (IOC1)	0010 0001	21	
I/O Control Register 0 (IOC0)	0000 00X0	0X	
Serial Port Control Register (SP_CON)	0000 1011	0B	
Baud Rate Register (BAUD_RATE)	0000 0000 0000 0001	0001	
I/O Control Register 2 (IOC2)	X00X X000	XX	
Watch Dog Timer Register (WATCH- DOG)	0000 0000	00	

Table 8: Special Function Register Reset Values			
Internal Register	Binary Reset State	Hexadecimal Reset Value	
Transmit Serial Port Buffer (SBUF (TX))	0000 0000	00	
HSO Command Register (HSO_command)	0000 0000	00	
HSO Time Register (HSO_time)	0000 0000 0000 0000	0000	
HSI Mode Register (HSI_mode)	1111 1111	FF	
PWM2 Control Register (PWM2_CTRL)	0000 0000	00	
PWM1 Control Register (PWM1_CTRL)	0000 0000	00	
EDAC Control and Status Register (EDAC_CS)	0000 0000	00	
Timer 3 Value Register (TIMER3)	0000 0000 0000 0000	0000	
Watchdog Timer Prescaler (WDT_SCALE)	0000 0000	00	
I/O Control Register 3 (IOC3)	1111 0000	F0	
Interrupt Priority Register (INT_PRI)	0000 0000	00	
PTS Service Register (PTSSRV)	0000 0000 0000 0000	0000	
PTS Select Register (PTSSEL)	0000 0000 0000 0000	0000	
Timer 2 Capture Register (T2CAPTURE)	0000 0000 0000 0000	0000	
Program Counter (PC)	0010 0000 1000 0000	2080	
Chip Configuration Register (CCR)	XX10 1111	XF	

Table 9: External I/O Reset State				
External I/O	I/O Function After Reset	I/O State During Reset	I/O State After Reset	
Address/Data Bus (AD15:0)	Address/Data Bus	Pulled High	Driven Output	
ALE ADV	ALE	Pulled High	Driven Output	
RD	RD	Pulled High	Driven Output	
WR WRL	WR	Pulled High	Driven Output	
Port 0 (P0.0-P0.3; P0.6) ECB(4:0)	[P0.0-P0.3; P0.6] and ECB(4:0)	Undefined Inputs ¹	Undefined I/O ^{1, 2}	
Port 0 (P0.4 and P0.5)	P0.4 and P0.5	Undefined Inputs ¹	Undefined Inputs ¹	
Port 0 (P0.7) EXTINT	P0.7	Undefined Input ¹	Undefined Input ¹	
NMI	NMI	Pulled Down	Pulled Down	
HSI.0 T2RST	HSI.0	Disabled Input ¹	Disabled Input ¹	
HSI.1 T2CLK	HSI.1	Disabled Input ¹	Disabled Input ¹	
HSI.2/HSO.4	Undefined	Disabled I/O ¹	Disabled I/O ¹	
HSI.3/HSO.5	Undefined	Disabled I/O ¹	Disabled I/O ¹	
HSO.0 through HSO.3	HSO.0-HSO.3	Pulled Down	Driven Low Outputs	
Port 1 (P1.0-P1.7) <u>PWM1; PWM2;</u> BREQ; HLDA; HOLD	P1.0-P1.7	Pulled Up	Pulled Up	
Port 2 (P2.0) TXD	TXD	Pulled Up	Driven High Output	
Port 2 (P2.1) RXD	RXD	Undefined Input ¹	Undefined Input ¹	
Port 2 (P2.2) EXTINT	P2.2 and EXTINT	Undefined Input ¹	Undefined Input ¹	
Port 2 (P2.3) T2CLK	P2.3 and T2CLK	Undefined Input ¹	Undefined Input ¹	
Port 2 (P2.4) T2RST	P2.4	Undefined Input ¹	Undefined Input ¹	

Table 9: External I/O Reset State			
External I/O	I/O Function After Reset	I/O State During Reset	I/O State After Reset
Port 2 (P2.5) PWM0	PWM0	Pulled Down	Driven Low Output
Port 2 (P2.6) T2UP-DN	P2.6	Pulled Up	Pulled Up
Port 2 (P2.7) T2CAPTURE	P2.7 and T2CAPTURE	Pulled Up	Pulled Up
EDACEN	EDACEN	Undefined Input ¹	Undefined Input ¹
ECB5	ECB5	Undefined I/O ¹	Undefined I/O ^{1,2}
READY	READY	Undefined Input ¹	Undefined Input ¹
BUSWIDTH	BUSWIDTH	Undefined Input ¹	Undefined Input ¹
BHE WRH	BHE	Pulled Up	Driven Output
CLKOUT	CLKOUT	Driven Output	Driven Output
INST	INST	Pulled Down	Driven Output
RESET	RESET	Pulled Low by System	Pulled Up

Notes:
1. These pins must not be left floating. Input voltages must not exceed V_{DD} during power-up.
2. Do not directly tie these pins to V_{DD} or GND; if EDACEN goes low, they may be driven by the UT80C196KD and bus contention may occur.





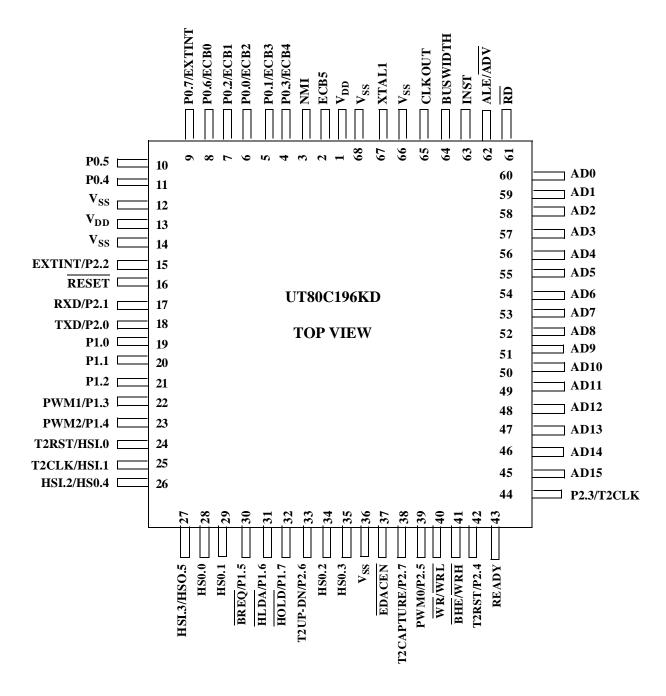


Figure 3. 68-pin Quad Flatpack Package

Legend	l for I/O fields:	TDI	= TTL compatible input
			(internally pulled low)
TO	= TTL compatible output	TB	= TTL compatible bidirectional
TI	= TTL compatible input	TUQ	= TTL compatible quasi-bidirectional
CI	= CMOS only input		(internally pulled high)
TUO	= TTL compatible output	TUB	= TTL compatible bidirectional
	(internally pulled high)		(internally pulled high)
TDO	= TTL compatible output	TUBS	= TTL compatible bidirectional Schmitt
	(internally pulled low)		Trigger (internally pulled high)
TUI	= TTL compatible input	PWR	$= +5V (V_{DD})$
	(internally pulled high)	GND	$= OV (V_{SS})$
			- (33)

	Table 10: 68-lead Flat Pack Pin Descriptions				
QFP Pin#	I/O	Name	Active	Description	
1	PWR	V _{DD}		Digital supply voltage (+5V). There are 2 V_{DD} pins, both of which must be connected.	
2	TB	ECB5 ¹		EDAC Check Bit 5. Asserting the EDACEN pin will cause the error detection and correction engine to pass the EDAC Check Bit 5 through pin 2 of the UT80C196KD.	
3	TDI	NMI	High	Non-Maskable Interrupt. A positive transition causes a vector through the NMI interrupt at location 203Eh. Assert NMI for at least 1 state time to guarantee acknowledgment by the interrupt controller.	
4	TI	P0.3		Port 0 Pin 3. An input only port pin that is read at location 0Eh in HWindow 0.	
	TB	ECB4 ¹		EDAC Check Bit 4. Asserting the EDACEN pin will cause the error detection and correction engine to pass the EDAC Check Bit 4 through pin 4 of the UT80C196KD.	
5	TI	P0.1		Port 0 Pin 1. An input only port pin that is read at location 0Eh in HWindow 0.	
	TB	ECB3 ¹		EDAC Check Bit 3. Asserting the EDACEN pin will cause the error detection and correction engine to pass the EDAC Check Bit 3 through pin 5 of the UT80C196KD.	
6	TI	P0.0		Port 0 Pin 0. An input only port pin that is read at location 0Eh in HWindow 0.	
	TB	ECB2 ¹		EDAC Check Bit 2. Asserting the $\overline{\text{EDACEN}}$ pin will cause the error detection and correction engine to pass the EDAC Check Bit 2 through pin 6 of the UT80C196KD.	

		Tab	le 10: 68-le	ad Flat Pack Pin Descriptions
QFP Pin#	I/O	Name	Active	Description
7	TI	P0.2		Port 0 Pin 2. An input only port pin that is read at location 0Eh in HWindow 0.
	TB	ECB1 ¹		EDAC Check Bit 1. Asserting the EDACEN pin will cause the error detection and correction engine to pass the EDAC Check Bit 1 through pin 7 of the UT80C196KD.
8	TI	P0.6		Port 0 Pin 6. An input only port pin that is read at location 0Eh in HWindow 0.
	TB	ECB0 ¹		EDAC Check Bit 0. Asserting the EDACEN pin will cause the error detection and correction engine to pass the EDAC Check Bit 0 through pin 8 of the UT80C196KD.
9	TI	P0.7		Port 0 Pin 7. An input only port pin that is read at location 0Eh in HWindow 0.
	TI	EXTINT	High	External Interrupt. Setting IOC1.1 = 1 enables pin 9 as the source for the external interrupt EXTINT. A rising edge on this pin will generate EXTINT (INT07, 200Eh). Assert EXTINT for at least 2 state times to ensure acknowledgment by the interrupt controller.
				During Power Down mode, asserting EXTINT places the chip back into normal operation, even if EXTINT is masked.
10	TI	P0.5		Port 0 Pin 5. An input only port pin that is read at location 0Eh in HWindow 0.
11	TI	P0.4		Port 0 Pin 4. An input only port pin that is read at location 0Eh in HWindow 0.
12	GND	V _{SS}		Digital circuit ground (0V). There are 4 V_{SS} pins, all of which must be connected and one additional recommeded V_{SS} connection.
13	PWR	V _{DD}		Digital supply voltage (+5V). There are 2 V_{DD} pins, both of which must be connected.
14	GND	V _{SS}		Digital circuit ground (0V). There are 4 V_{SS} pins, all of which must be connected and one additional recommeded V_{SS} connection.

		Tabl	le 10: 68-le	ad Flat Pack Pin Descriptions
QFP Pin#	I/O	Name	Active	Description
15	TI	P2.2		Port 2 Pin 2. An input only port pin that is written at location 10h of HWindow 0. P2.2 will always generate EXTINT1 (INT13, 203Ah) unless masked by the INT_MASK1 register. Assert EXTINT1 for at least 2 state times to guarantee acknowl- edgment by the interrupt controller.
	TI	EXTINT	High	External Interrupt. Setting IOC1.1 = 0 enables pin 15 as the source for the external interrupt EXTINT. A rising edge on this pin will generate EXTINT (INT07, 200Eh). Assert EXTINT for at least 2 state times to ensure acknowledgment by the interrupt controller.During Power Down mode, asserting EXTINT places the chip
				back into normal operation, even if EXTINT is masked.
16	TUBS	RESET	Low	Master Reset. The first external reset signal supplied to the UT80C196KD must be active for at least 16 state times. All subsequent $\overrightarrow{\text{RESET}}$ assertions need only be active for 1 state time because the UT80C196KD will continue driving the $\overrightarrow{\text{RESET}}$ signal for an additional 16 state times. See section 1.1.2 for more information on the $\overrightarrow{\text{RESET}}$ function of the UT80C196KD.
17	TI	P2.1		Port 2 Pin 1. An input only port pin that is read at location 10h of HWindow 0.
				Setting SPCON.3 = 0 enables the P2.1 function of pin 17.
	ТВ	RXD		RXD is a bidirectional serial data port. When operating in Serial Modes 1, 2, and 3, RXD receives serial data. When using Serial Mode 0, RXD operates as an input and an open-drain output for data.Setting SPCON.3 = 1 enables the RXD function of pin 17.
18 ²	TUO	P2.0		Port 2 Pin 0. An output only port pin that is written at location
18	100	12.0		10h of HWindow 0.
				Setting IOC1.5 = 0 enables the P2.0 function of pin 18.
	TUO	TXD		Transmit Serial Data (TXD). When set to Serial Mode 1, 2, or 3, TXD transmits serial port data. When using Serial Mode 0, TXD is used as the Serial Clock output.
				Setting IOC1.5 = 1 enables the TXD function of pin 18.
	TUI	ICT	Low	In-Circuit Test. The UT80C196KD will enter the In-Circuit Test mode if this pin is held low during the rising edge of $\overrightarrow{\text{RESET}}$.

		Tabl	le 10: 68-le	ad Flat Pack Pin Descriptions	
QFP Pin#	I/O	Name	Active	Description	
19	TUQ	P1.0		Port 1 Pin 0. A quasi-bidirectional port pin that is read and writ- ten at location 0Fh of HWindow 0.	
20	TUQ	P1.1		Port 1 Pin 1. A quasi-bidirectional port pin that is read and writ- ten at location 0Fh of HWindow 0.	
21	TUQ	P1.2		Port 1 Pin 2. A quasi-bidirectional port pin that is read and written at location 0Fh of HWindow 0.	
22	TUQ	P1.3		Port 1 Pin 3. A quasi-bidirectional port pin that is read and writ- ten at location 0Fh of HWindow 0.	
				Setting IOC $3.2 = 0$ enables the P1.3 function of pin 22.	
	TUO	PWM1		Pulse Width Modulator (PWM) Output 1. The output signal will be a waveform whose duty cycle is programmed by the PWM1_CONTROL register, and the frequency is selected by IOC2.2.	
				Setting IOC3.2 = 1 enables the PWM1 function of pin 22.	
23	TUQ	P1.4		Port 1 Pin 4. A quasi-bidirectional port pin that is read and written at location 0Fh of HWindow 0.	
				Setting IOC3.3 = 0 enables the P1.4 function of pin 23.	
	TUO	PWM2		Pulse Width Modulator (PWM) Output 2. The output signal will be a waveform whose duty cycle is programmed by the PWM2_CONTROL register, and the frequency is selected by IOC2.2.	
				Setting IOC3.3 = 1 enables the PWM2 function of pin 23.	
24	TI	HSI.0		High Speed Input Module, input pin 0. Unless masked, a rising edge on this input will generate the HSI.0 Pin interrupt (INT04, 2008h). Assert the HSI.0 pin for at least 2 state times to ensure acknowledgment by the interrupt controller.	
				Setting $IOC0.0 = 1$ enables pin 24 as an HSI input, and allows events on this pin to be loaded into the HSI FIFO.	
	TI	T2RST	High	Timer 2 Reset. A rising edge on the T2RST pin resets Timer 2.	
				To enable the T2RST function of pin 24, set $IOC0.3 = 1$ and $IOC0.5 = 1$.	

		Tabl	e 10: 68-le	ad Flat Pack Pin Descriptions	
QFP Pin#	I/O	Name	Active	Description	
25	TI	HSI.1		High Speed Input Module, input pin 1.	
				Setting IOC $0.2 = 1$ enables pin 25 as an HSI input, and allows events on this pin to be loaded into the HSI FIFO.	
	TI	T2CLK		Timer 2 Clock.	
				Setting IOC $0.7 = 1$ and IOC $3.0 = 0$ enables pin 25 to function as the Timer 2 clock source.	
26	ТО	HSO.4		High Speed Output Module, output pin 4. This pin can simulta- neously operate in the HSI and HSO modes of operation. As a result, this pin acts as an output that the HSI monitors.	
				Setting IOC1.4 = 1 enables the HSO.4 function of pin 26.	
	TI	HSI.2		High Speed Input Module, input pin 2. This pin can simulta- neously operate in the HSI and HSO modes of operation. As a result, this pin can monitor events on the HSO.	
				Setting IOC $0.4 = 1$ enables pin 26 as an HSI input pin, and allows events on this pin to be loaded into the HSI FIFO.	
27	ТО	HSO.5		High Speed Output Module, output pin 5. This pin can simulta- neously operate in the HSI and HSO modes of operation. As a result, this pin acts as an output that the HSI monitors.	
				Setting IOC1.6 = 1 enables the HSO.5 function of pin 27.	
	TI	HSI.3		High Speed Input Module, input pin 3. This pin can simulta- neously operate in the HSI and HSO modes of operation. As a result, this pin can monitor events on the HSO.	
				Setting IOC $0.6 = 1$ enables pin 27 as an HSI input pin, and allows events on this pin to be loaded into the HSI FIFO.	
28	TDO	HSO.0		High Speed Output Module, output pin 0. The HSO.0 pin is a dedicated output for the HSO module.	
29	TDO	HSO.1		High Speed Output Module, output pin 1. The HSO.1 pin is a dedicated output for the HSO module.	

		Tab	le 10: 68-le	ad Flat Pack Pin Descriptions
QFP Pin#	I/O	Name	Active	Description
30	TUQ	P1.5		Port 1 Pin 5. A quasi-bidirectional port pin that is read and writ- ten at location 0Fh of HWindow 0.
				Setting WSR.7 = 0 enables the P1.5 function of pin 30.
	TUO	BREQ	Low	Bus Request. The $\overline{\text{BREQ}}$ output signal asserts during a $\overline{\text{HOLD}}$ cycle when the internal bus controller has a pending external memory cycle.
				$\frac{\text{During a HOLD cycle, BREQ will not be asserted until the}{\text{HLDA signal is asserted. Once asserted, BREQ does not deas-sert until the HOLD signal is released.}$
				Setting WSR.7 = 1 enables the \overline{BREQ} function of pin 30.
31 ²	TUQ	P1.6		Port 1 Pin 6. A quasi-bidirectional port pin that is read and writ- ten at location 0Fh of HWindow 0.
				Setting WSR.7 = 0 enables the P1.6 function of pin 31.
	TUO	HLDA	Low	Bus Hold Acknowledge. The UT80C196KD asserts the HLDA signal as a result of another device activating the HOLD signal. By asserting this signal, the UT80C196KD is indicating that it has released the bus.
				Setting WSR.7 = 1 enables the $\overline{\text{HLDA}}$ function of pin 31.
32	TUQ	P1.7		Port 1 Pin 7. A quasi-bidirectional port pin that is read and writ- ten at location 0Fh of HWindow 0.
				Setting WSR.7 = 0 enables the P1.7 function of pin 32.
	TUI	HOLD	Low	Bus Hold. The $\overline{\text{HOLD}}$ signal is used to request control of the bus by another DMA device.
				Setting WSR.7 = 1 enables the $\overline{\text{HOLD}}$ function of pin 32.
33	TUQ	P2.6		Port 2 Pin 6. A quasi-bidirectional port pin that is read and writ- ten at location 10h of HWindow 0.
				Setting IOC2.1 = 0 enables the P2.6 function of pin 33.
	TUI	T2UP-DN		Timer 2 Up or Down. The T2UP-DN pin will dynamically change the direction that Timer 2 counts.
				T2UP-DN = 1 then Timer 2 counts down. T2UP-DN = 0 then Timer 2 counts up.
				Setting IOC2.1 = 1 enables the T2UP-DN function of pin 33. When IOC2.1 = 0, Timer 2 will only count up.

		Tabl	e 10: 68-le	ad Flat Pack Pin Descriptions	
QFP Pin#	I/O	Name	Active	Description	
34	TDO	HSO.2		High Speed Output Module, output pin 2. The HSO.2 pin is a dedicated output for the HSO module.	
35	TDO	HSO.3		High Speed Output Module, output pin 3. The HSO.3 pin is a dedicated output for the HSO module.	
36	GND	V _{SS}		 High Speed Output Module, output pin 3. The HSO.3 pin is a dedicated output for the HSO module. Digital circuit ground (0V). There are 4 V_{SS} pins, all of which must be connected and one additional recommeded V_{SS} connection. EDAC Enable. Asserting the EDACEN signal activates the error detection and correction engine. This causes the UT80C196KD to include ECB(5:0) as the EDAC check bit pins in all external memory cycles. Port 2 Pin 7. A quasi-bidirectional port pin that is read and written at location 10h of HWindow 0. Timer 2 Capture. A rising edge on this pin loads the value of Timer 2 into the T2CAPTURE register, and generates a Timer 2 Capture interrupt (INT11, 2036h). Assert the T2CAPTURE signal for at least 2 state times to guarantee acknowledgment by the interrupt controller. Using INT_Mask1.3 controls whether or not a rising edge causes an interrupt. Port 2 Pin 5. An output only port pin that is written at location 	
37	TI	EDACEN	Low	error detection and correction engine. This causes the UT80C196KD to include ECB(5:0) as the EDAC check bit pins	
38	TUQ	P2.7		Port 2 Pin 7. A quasi-bidirectional port pin that is read and writ- ten at location 10h of HWindow 0.	
	TUQ	T2CAPTURE	High	Timer 2 into the T2CAPTURE register, and generates a Timer 2 Capture interrupt (INT11, 2036h). Assert the T2CAPTURE sig- nal for at least 2 state times to guarantee acknowledgment by the interrupt controller. Using INT_Mask1.3 controls whether or not	
39	TDO	P2.5			
	TDO	PWM0		Pulse Width Modulator (PWM) Output 0. The output signal will be a waveform whose duty cycle is programmed by the PWM0_CONTROL register, and the frequency is selected by IOC2.2. Setting IOC1.0 = 1 enables the PWM0 function of pin 39.	
40 ²	TUO	WR	Low	Write. The \overline{WR} signal indicates that an external write is occurring. Activation of this signal only occurs during external memory writes.	
				Setting CCR.2 = 1 enables the \overline{WR} function of pin 40.	
	TUO	WRL	Low	Write Low. The $\overline{\text{WRL}}$ signal is activated when writing the low byte of a 16-bit wide word, and is always asserted for 8-bit wide memory writes.	
				Setting CCR.2 = 0 enables the \overline{WRL} function of pin 40.	

		Tab	le 10: 68-le	ad Flat Pack Pin Descriptions
QFP Pin#	I/O	Name	Active	Description
41	TUO	BHE	Low	Byte High Enable. The assertion of the \overline{BHE} signal will occur for all 16-bit word writes, and high byte writes in both 8- and 16- bit wide bus cycles. Setting CCR.2 = 1 enables the \overline{BHE} function of pin 41.
	TUO	WRH	Low	Write High. The WRH signal is asserted for high byte writes, and word writes for 16-bit wide bus cycles. Additionally, WRH is asserted for all write operations when using an 8-bit wide bus cycle. Setting CCR.2 = 0 enables the WRH function of pin 41.
42	TI	P2.4		Port 2 Pin 4. An input only port pin that is read at location 10h of HWindow 0.
	TI	T2RST	High	Timer 2 Reset. Asserting the T2RST signal will reset Timer 2.
				To enable the T2RST function of pin 42, set $IOC0.3 = 1$ and $IOC0.5 = 0$.
43	TI	READY	High	READY input. The READY signal is used to lengthen memory cycles by inserting "wait states" for interfacing to slow peripher- als. When the READY signal is high, no "wait states" are gener- ated, and the CPU operation continues in a normal fashion. If READY is low during the falling edge of CLKOUT, the mem- ory controller inserts "wait states" into the memory cycle. "Wait state" generation will continue until a falling edge of CLKOUT detects READY as logically high, or until the number of "wait states" is equal to the number programmed into CCR.4 and CCR.5. Note: The READY signal is only used for external memory accesses, and is functional during the CCR fetch.
44	TI	P2.3		Port 2 Pin 3. An input only port pin that is read at location 10h of HWindow 0.
	TI	T2CLK		Timer 2 Clock input. Setting IOC0.7 = 0 and IOC3.0 = 0enables this pin as the external clock source for Timer 2.IOC0.7:IOC3.0:Timer 2 Clock Source:X1Internal Clock Source00P2.3 External Clock Source10HSI.1 External Clock Source
45	TUB	AD15		Bit 15 of the Address/Data bus. This pin is a dedicated address pin when operating with 8-bit wide bus cycles. For 16-bit wide bus cycles, this pin is used as multiplexed address and data.

Table 10: 68-lead Flat Pack Pin Descriptions						
QFP Pin#	I/O	Name	Active	Description		
46	TUB	AD14		Bit 14 of the Address/Data bus. This pin is a dedicated address pin when operating with 8-bit wide bus cycles. For 16-bit wide bus cycles, this pin is used as multiplexed address and data.		
47	TUB	AD13		Bit 13 of the Address/Data bus. This pin is a dedicated address pin when operating with 8-bit wide bus cycles. For 16-bit wide bus cycles, this pin is used as multiplexed address and data.		
48	TUB	AD12		Bit 12 of the Address/Data bus. This pin is a dedicated address pin when operating with 8-bit wide bus cycles. For 16-bit wide bus cycles, this pin is used as multiplexed address and data.		
49	TUB	AD11		Bit 11 of the Address/Data bus. This pin is a dedicated address pin when operating with 8-bit wide bus cycles. For 16-bit wide bus cycles, this pin is used as multiplexed address and data.		
50	TUB	AD10		Bit 10 of the Address/Data bus. This pin is a dedicated address pin when operating with 8-bit wide bus cycles. For 16-bit wide bus cycles, this pin is used as multiplexed address and data.		
51	TUB	AD9		Bit 9 of the Address/Data bus. This pin is a dedicated address pin when operating with 8-bit wide bus cycles. For 16-bit wide bus cycles, this pin is used as multiplexed address and data.		
52	TUB	AD8		Bit 8 of the Address/Data bus. This pin is a dedicated address pin when operating with 8-bit wide bus cycles. For 16-bit wide bus cycles, this pin is used as multiplexed address and data.		
53	TUB	AD7		Bit 7 of the Address/Data bus. This pin is used as multiplexed address and data for both 8- and 16-bit wide bus cycles.		
54	TUB	AD6		Bit 6 of the Address/Data bus. This pin is used as multiplexed address and data for both 8- and 16-bit wide bus cycles.		
55	TUB	AD5		Bit 5 of the Address/Data bus. This pin is used as multiplexed address and data for both 8- and 16-bit wide bus cycles.		
56	TUB	AD4		Bit 4 of the Address/Data bus. This pin is used as multiplexed address and data for both 8- and 16-bit wide bus cycles.		
57	TUB	AD3		Bit 3 of the Address/Data bus. This pin is used as multiplexed address and data for both 8- and 16-bit wide bus cycles.		
58	TUB	AD2		Bit 2 of the Address/Data bus. This pin is used as multiplexed address and data for both 8- and 16-bit wide bus cycles.		
59	TUB	AD1		Bit 1 of the Address/Data bus. This pin is used as multiplexed address and data for both 8- and 16-bit wide bus cycles.		
60	TUB	AD0		Bit 0 of the Address/Data bus. This pin is used as multiplexed address and data for both 8- and 16-bit wide bus cycles.		

		Tabl	le 10: 68-le	ead Flat Pack Pin Descriptions
QFP Pin#	I/O	Name	Active	Description
61 ²	TUO	RD	Low	Read. The $\overline{\text{RD}}$ signal is an output to external memory that is only asserted during external memory reads.
62 ²	TUO	ALE	High	Address Latch Enable. The ALE signal is an output to external memory that is only asserted during external memory accesses. ALE is used to specify that valid address information is available on the address/data bus, and signals the start of a bus cycle. ALE is used by an external latch to demultiplex the address from the address/data bus. Setting CCR.3 = 1 enables the ALE function of pin 62.
	TUO	ADV	Low	Address Valid. The \overline{ADV} signal is an output to external memory that is only asserted during external memory accesses. \overline{ADV} is driven high to specify that valid address information is available on the address/data bus. The \overline{ADV} signal is held low during the data transfer portion of the bus cycle, and is driven high when the bus cycle completes. \overline{ADV} is used by an external latch to demultiplex the address from the address/data bus. Setting CCR.3 = 0 enables the \overline{ADV} function of pin 62.
63	TDO	INST	High	Instruction Fetch. The INST signal indicates the type of external memory cycle being performed. The INST signal will be high during instruction fetches, and will be low for data fetches.
				Note: CCB bytes and Interrupt vectors are considered data .
64	TI	BUSWIDTH		 Bus Width. The BUSWIDTH pin dynamically modifies the width of bus cycles. When a high logic value is supplied, the bus width will be set to 16-bits wide. When a low logic level is supplied, the bus width will be set to 8-bits wide. Setting CCR.1 = 1 enables the BUSWIDTH pin. Setting CCR.1 = 0 disables the BUSWIDTH pin. As a result, the UT80C196KD will only perform 8-bit wide bus cycles.
65	TUO	CLKOUT		Clock Output. The CLKOUT signal is the output of the internal clock. This signal has a 50% duty cycle, and runs at $1/2$ the frequency of the system clock input to XTAL1. Setting IOC3.1 = 0 will enable the CLKOUT output signal.
66	GND	V _{SS} ³		Digital circuit ground (0V). Recommended connection for signal integrity improvement. There are 4 V_{SS} pins, all of which must be connected.
67	CI	XTAL1		External oscillator or clock input to the UT80C196KD. The XTAL1 input is fed to the on-chip clock generator.
68	GND	V _{SS}		Digital circuit ground (0V). There are 4 V_{SS} pins, all of which must be connected and one additional recommeded V_{SS} connection.

Notes:

These pins should be pulled high or low when using EDAC (i.e. EDACEN = 0) to prevent the voltages on these pins from floating to the switching threshold of the input buffers during long read cycles.
 These pins must be high on the rising edge of RESET in order to avoid entering any test modes.
 This pin is a recommended V_{SS} connection. The remaining 4 V_{SS} pins are required to be tied to the circuit card ground plane.

2.0 ABSOLUTE MAXIMUM RATINGS $^{\rm 1}$

(Referenced to V_{SS})

SYMBOL	PARAMETER	LIMITS	UNITS
V _{DD}	DC Supply Voltage	-0.3 to 6.0	V
V _{I/O} ²	Voltage on Any Pin	-0.3 to V _{DD} +0.3V	V
T _{STG}	Storage Temperature	-65 to +150	°C
T _J	Maximum Junction Temperature	175	°C
$\Theta_{\rm JC}$	Thermal Resistance, Junction-to-Case ³	16	°C/W
I _I ²	DC Input Current	±10	mA

Notes:

1. Stresses outside the listed absolute maximum ratings may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond limits indicated in the operational sections of this specification is not recommended. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

These ratings are provided as design guidelines. They are not guaranteed by test or characterization.
 Test per MIL-STD-883, Method 1012.

3.0 DC ELECTRICAL CHARACTERISTICS

 $(V_{DD} = 5.0V \pm 10\%)$ (T_C = -55°C to +125°C for "C" screening and -40°C to +125°C for "W" screening)

SYMBOL	PARAMETER	CONDITION	MINIMUM	MAXIMUM	UNIT
V _{IL}	Low-level Input Voltage (except XTAL1, RESET)			0.8	V
V _{IH}	High-level Input <u>Voltage</u> (except XTAL1, RESET)		2.2		V
$V_{\rm IH1}$	High-level Input Voltage (XTAL1)		.7V _{DD}		V
V _{IL1}	Low-level Input Voltage (XTAL1)			.3V _{DD}	V
V_{T+}	Positive Going Threshold RESET		.5V _{DD}	.7V _{DD}	V
V _{T-}	Negative Going Threshold RESET		.2V _{DD}	.4V _{DD}	V
V _H	Typical Range of Hysteresis ⁶ RESET		.9		V
V _{OL}	Low-level Output Voltage (CMOS load)	$I_{OL} = 200 \mu A^6$		0.3	v
	(TTL load)	$I_{OL} = 4.0 \text{mA}$		0.4	v
V _{OH}	High-level Output Voltage ⁸ (CMOS load) (Standard outputs) (TTL load)	$I_{OH} = -200 \mu A^6$ $I_{OH} = -4.0 m A$	V _{DD} 3 3.8		V V
I _{OHI}	High-level Output Current ¹ (Open drain outputs with pullups)	$V_{OH} = V_{DD}3^{6}$ $V_{OH} = V_{DD}9$	-20 -60		μA μA
I _{IL}	Logical 0 Input Current ² (Test mode entry)	$V_{IN} = V_{IH}$	-550	-120	μΑ
I _{LI}	I/O Leakage Current, standard inputs/outputs in Z state	$V_{IN} = V_{SS}$ or V_{DD}	-5	+5	μΑ
I _{LI1}	I/O Leakage Current, with pullups ³	$V_{IN} = V_{SS}$	-800	-150	μΑ
I _{LI2}	I/O Leakage Current, with pulldowns ⁴	$V_{IN} = V_{DD}$	200	1500	μΑ
C _{IO}	Pin Capacitance ⁶	@ 1MHZ, 25°C		15	pF
AI _{DD}	Active Power Supply Current	Clk@20MHz, typical program flow		110	mA
QI _{DD}	Quiescent Power Supply Current	Unloaded -55° to +25℃ Outputs +125℃		20 1000	μA
I _{DDPD}	Power Supply Current in Power Down	No Active I/O, Clk@20MHz		6	mA
I _{DDIDLE}	Power Supply Current in Idle Mode			55	mA
I _{DDRESET}	Power Supply Current in Reset	CLK @20 MHz, $\overline{\text{RESET}} \leq V_{\text{IL}}$		65	mA
I _{OS}	Short Circuit output current (except for pins listed in Note 5) ^{6,7}		-100	130	mA
I _{OS1}	Short Circuit output current ^{5,6,7}	$V_{DD} = 5.5 V$	-200	250	mA

Notes:

- 1. Open-drain outputs with pull<u>ups incl</u>ude Port 1, P2.6 and P2.7. 2. Test modes are entered at the RESET rising edge by applying V_{IL} to one or more of the following pins: TXD, RD, WR, HLDA. To avoid entering a test mode, ensure that these pins remain above V_{IH} at the rising edge of RESET.
- 3. Inputs/outputs with pullup resistors include: RESET, Port 1, P2.0, P2.6, P2.7, WR, BHE, AD0-15, RD, ALE, CLKOUT.
- Inputs/outputs will pulldown <u>resistors include: NMI, HS0.0-HS0.3, P2.5, INST.</u>
 The I_{SO1} spec applies to pins RESET, BHE, RD, CLKOUT.
- 6. Tested only at initial qualification and after any design or process changes which may affect this characteristic.
- 7. Not more than one output may be shorted at a time for maximum duration of one second.
- 8. For standard outputs not covered by IOHI spec.

5.0 AC CHARACTERISTICS READ CYCLE

 $(V_{DD} = 5.0V \pm 10\%)$ (T_C = -55°C to +125°C for "C" screening and -40°C to +125°C for "W" screening)

SYMBOL	PARAMETER	MINIMUM	MAXIMUM	UNI
$t_{\rm AVYV}^{5}$	Address VALID to READY setup		2T _{OSC} - 30	ns
t _{YLYH} ⁵	Non-READY time	No upper limit		ns
t _{CLYX} ^{1,5}	READY hold after CLKOUT low	0	2T _{OSC} - 20	ns
t _{LLYX} ^{1,5}	READY hold after ALE low	T _{OSC}	3T _{OSC} - 20	ns
t _{AVGV} ⁵	Address valid to BUSWIDTH setup		2T _{OSC} - 30	ns
t _{CLGX} ⁵	BUSWIDTH hold after CLKOUT low	0		ns
$t_{\rm AVDV}^{2,5}$	Address valid to input data valid		3T _{OSC} - 29	ns
t _{RLDV} ²	RD Active to input data valid	5 (see Note 5)	T _{OSC} - 26	ns
t _{CLDV} ⁵	CLKOUT low to input data valid	5	T _{OSC} - 26	ns
t _{RHDZ} ⁵	End of RD to input data float	0	T _{OSC} -10	ns
t _{RXDX} ⁵	Data hold after RD inactive	0	T _{OSC} -10	ns
f _{OSC} ⁵	Frequency on XTAL1	1 (see Note 7)	20 (see Note 6)	Mhz
T _{OSC} ⁵	XTAL1 period (1/f _{OSC})	50 (see Note 6)	1000 (see Note 7)	ns
t _{XHCH}	XTAL1 high to CLKOUT high or low	0	+25	ns
t _{CLCL} ⁶	CLKOUT cycle time	2T _{OSC} Typical		ns
t _{CHCL} ⁵	CLKOUT high period	T _{OSC} - 10	T _{OSC} +10	ns
t _{CLLH}	CLKOUT falling edge to ALE rising	-5	+15	ns
t _{LLCH} 5	ALE falling edge to CLKOUT rising	-10	+10	ns
t _{LHLH} ^{2, 6}	ALE cycle time	4T _{OSC} Typical		ns
t _{LHLL} ⁵	ALE high period	T _{OSC} - 10	T _{OSC} +15	ns
$t_{\rm AVLL}^{5}$	Address setup to ALE falling edge	T _{OSC} - 15		ns
t _{LLAX}	Address hold after ALE falling edge	T _{OSC} - 20	T _{OSC} +5	ns
t _{LLRL}	ALE falling edge to RD falling edge	T _{OSC} - 5	T _{OSC} +10	ns
t _{RLCL}	RD low to CLKOUT falling edge	-5	+10	ns
t _{RLRH} ²	RD low period	T _{OSC} - 5		ns
t _{RHLH} ^{3,5}	RD rising edge to ALE rising edge	T _{OSC} -10	T _{OSC} +10	ns
t _{RLAZ} 5	RD low to address float	-5	+5	ns

t _{LLWL} ⁵	ALE falling edge to \overline{WR} falling edge	T _{OSC} - 10	T _{OSC} +10	ns
t _{CLWL}	CLKOUT low to WR falling edge	-5	+10	ns
t _{QVWH} ²	Data stable to WR rising edge	T _{OSC} - 10	T _{OSC} +10	ns
t _{CHWH} ⁵	CLKOUT high to WR rising edge	-10	+15	ns
t _{WLWH} ^{2,5}	WR low period	T _{OSC} - 10		ns
t _{WHQX} 5	Data hold after WR rising edge	T _{OSC} - 10	T _{OSC} +10	ns
t _{WHLH} ^{3,5}	WR rising edge to ALE rising edge	T _{OSC} - 10	T _{OSC} +10	ns
t _{WHBX} 5	BHE, INST after WR rising edge	T _{OSC} - 10	T _{OSC} +10	ns
t _{WHAX} ^{4,5}	AD8-15 HOLD after WR rising	T _{OSC} - 25		ns
t _{RHBX} 5	BHE, INST after RD rising edge	T _{OSC} - 10	T _{OSC} +10	ns
t _{RHAX} 4,5	AD8-15 HOLD after RD rising	T _{OSC} - 25		ns
t _{AVENV} 5	Address valid to EDACEN valid		2T _{OSC} -30	ns
t _{LHENX} 5	EDACEN hold after ALE high	0		ns
t _{AVEV} ^{2,5}	Address valid to EDAC input valid		3T _{OSC} -29	ns
t _{RXEX} ⁵	EDAC hold after \overline{RD} inactive	0	T _{OSC} -10	ns
t _{EVWH} ^{2,5}	EDAC output stable to WR rising	T _{OSC} -10	T _{OSC} +10	ns
t _{WHEX} 5	EDAC output hold after WR rising	T _{OSC} -10	T _{OSC} +10	ns

Note:

* Post-radiation performance guaranteed at 25 °C per MIL-STD-883 Method 1019 at 1.0E5 rads(Si).

1. If max exceeded, additional wait state occurs. 2. If wait states are used, add 2 $T_{OSC} *N$, where N = number of wait states.

Assuming back-to-back bus cycles.
 Solution and after any design or process changes which may affect this characteristic.
 Tested only at initial qualification, and after any design or process changes which may affect this characteristic.
 These specs are verified using functional vectors (strobed) only.
 Low speed tests performed at 5MHz. 1MHz operation is guaranteed by design.

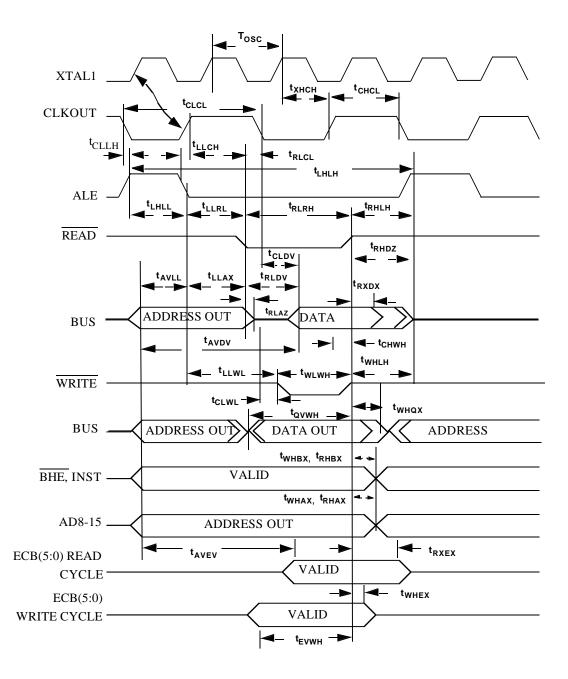


Figure 4. System Bus Timings

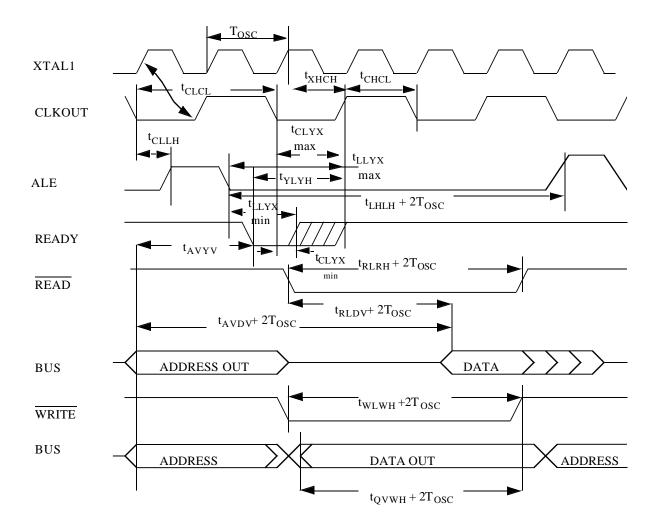


Figure 5. READY Timing (One Wait State)

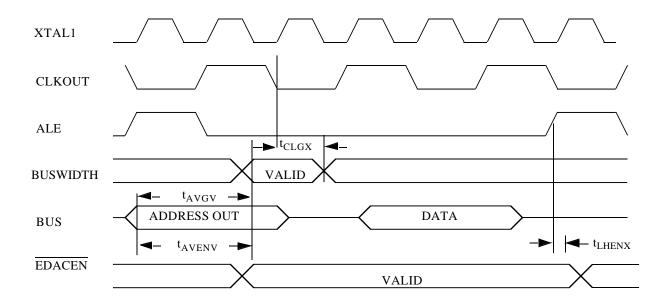


Figure 6. BUSWIDTH and EDACEN Timings

6.0 XTAL1 CLOCK DRIVE TIMING CHARACTERISTICS

SYMBOL	PARAMETER	MINIMUM	MAXIMUM	UNIT
f_{OSC}	Oscillator Frequency	1 ^(note 1)	20	MHz
T _{OSC}	Oscillator Period	50	1000 ^(note 1)	ns
t _{OSCH}	High Time	17 ^(note 1)		ns
toscl	Low Time	17 ^(note 1)		ns
t _{OSCR}	Rise Time		10 ^(note 2)	ns
t _{OSCF}	Fall Time		10 ^(note 2)	ns

Note: 1. Tested only at initial qualification, and after any design or process changes which may affect this characteristic. 2. Supplied as a design limit, but not guaranteed or tested.

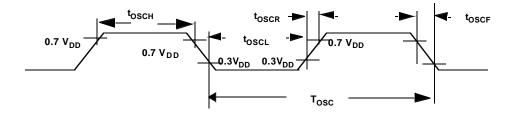


Figure 7. External Clock Drive Timing Waveforms

Table 11. DC Specifications in Hold

DESCRIPTION	MIN	MAX	CONDITIONS
Pullups on ADV, RD, WR, WRL, BHE, ALE	6.9K	36.7K	$V_{DD} = 5.5 V, V_{IN} = V_{SS}$
Pulldown on INST	3.7K	27.5K	$V_{DD} = 5.5 V, V_{IN} = V_{DD}$

Note: 1.Tested only at initial qualification, and after any design or process changes which may affect this characteristic.

7.0 HOLD/HLDA Timings

SYMBOL	PARAMETER	MINIMUM	MAXIMUM	UNIT
t _{HVCH} ¹	HOLD Setup	25		ns
t _{CLHAL} 1	CLKOUT low to HLDA low	-15	15	ns
t _{CLBRL} ¹	CLKOUT low to BREQ low	-15	15	ns
t _{HALAZ} ¹	HLDA low to address float		10	ns
t _{HALBZ} ¹	$\overline{\text{HLDA}} \text{ low to } \overline{\text{BHE}}, \text{ INST}, \overline{\text{RD}}, \overline{\text{WR}}$ driven weakly		15	ns
t _{CLHAH} 1	CLKOUT low to HLDA high	-15	15	ns
t _{CLBRH} ¹	CLKOUT low to BREQ high	-15	15	ns
t _{HAHAX} ¹	HLDA high to address no longer float	-15		ns
t _{HAHBV} 1	$\overline{\text{HLDA}}$ high to $\overline{\text{BHE}}$, INST, $\overline{\text{RD}}$, $\overline{\text{WR}}$ valid	-10		ns
t _{CLLH} ¹	CLKOUT low to ALE high	-5	15	ns

Note:

1. Tested only at initial qualification, and after any design or process changes which may affect this characteristic.

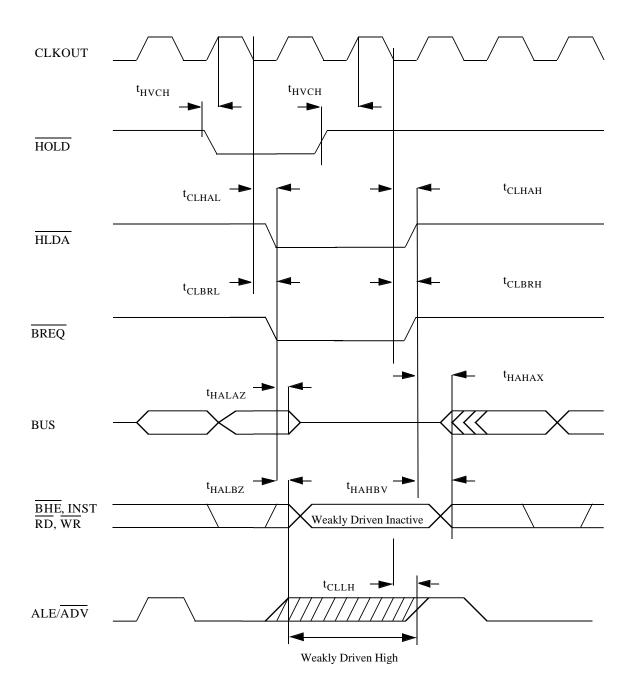
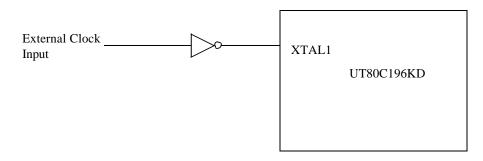


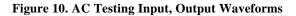
Figure 8. DC Specifications In Hold

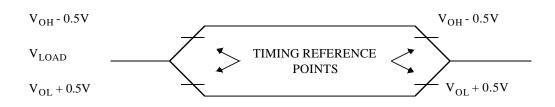






AC Testing inputs are driven at V_{DD} for a Logic "1" and 0.0V for a Logic "0". Timing measurements are made at 1.4V.





For timing purposes a port pin is no longer floating when it changes to a voltage outside the reference points shown and begins to float when it changes to a voltage inside the reference points shown. $I_{OL} = 4mA$, $I_{OH} = -4mA$.



SYMBOL	PARAMETER	MINIMUM	MAXIMUM	UNIT
t _{XLXL} ²	Serial port clock period (BRR > 8002H)	6 T _{OSO}	c typical	ns
t _{XLXH} 1	Serial port clock falling edge to rising edge (BRR \geq 8002H)	4 T _{OSC} -50	4 T _{OSC} +50	ns
t _{XLXL} ²	Serial port clock period (BRR = 8001H)	4 T _{OSC}	typical	ns
t _{XLXH} ¹	Serial port clock falling edge to rising edge (BRR = 8001H)	2 T _{OSC} -50	2 T _{OSC} +50	ns
t _{QVXH} ¹	Output data valid to clock rising edge	2 T _{OSC} -50		ns
t _{XHQX} ¹	Output data hold after clock rising edge	2 T _{OSC} -50		ns
t _{XHQV} ¹	Next output data valid after clock rising edge		2 T _{OSC} +50	ns
t _{DVXH} ¹	Input data setup to clock rising edge	T _{OSC} +50		ns
t _{XHDX} ¹	Input data hold after clock rising edge	0		ns
t _{XHQZ} ¹	Last clock rising to output float	2 T _{OSC} -10	2 T _{OSC} +10	ns

 Table 12. Serial Port Timing

Note :

1. Tested only at initial qualification, and after my design or process changes which may affect this characteristic.

2. These specs are verified functional vectors (strobed) only.

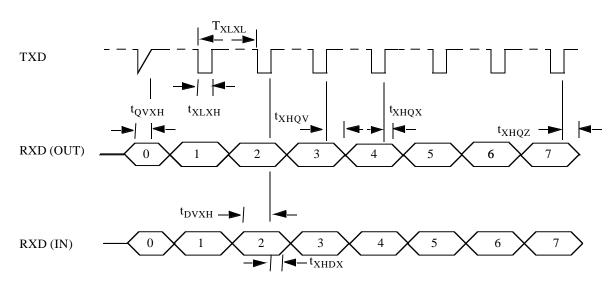


Figure 12. Serial Port Waveform - Shift Register Mode

APPENDIX A Difference Between Industry Standard and UT80C196KD

1.0 UT80C196KD DIFFERENCES TO INDUSTRY STANDARD 80C196KD

1.1 Analog to Digital Converter

The Analog to Digital Converter will not be implemented in the UT80C196KD.

1.3 Clocking

The XTAL2 output is not used and the UT80C196KD expects the input on the XTAL 1 to be a valid digital clock signal. The clock should be stable before reset is removed or Power Down mode is exited. In Power Down mode, a small number of gates will be clocked by the XTAL1 input. The UT80C196KD will drive XTAL2 low when not in test mode.

1.4 CCB Read after Reset

The CCB fetch after Reset will be a normal fetch as if the chosen bus width is selectable based on the BUSWIDTH input. Systems with an 8-bit wide interface should tie BUSWIDTH to ground. Systems that use BUSWIDTH should perform a normal decode based on the memory configuration of the system. The Industry Standard 80C196KD treats the CCB fetch as an 8-bit fetch (driving the upper 8-bits with address 20H) regardless of the state of BUSWIDTH.

1.5 Internal Program Memory

The UT80C196KD does not have internal program memory, and pin 2 (EA) will be ignored for choosing between internal and external program reads. The user may tie this pin to ground for compatibility reasons, unless EDAC is enabled.

1.6 Ports 3 and 4

Since the UT80C196KD will not have internal program memory, Ports 3 and 4 will always be used as the multiplexed Address and Data bus. Therefore, these ports will not be configured as I/O ports, and the bidirectional port function of these pins will not be implemented. The pins will only be configured as Address and bidirectional data pins.

1.7 Built in EDAC

The UT80C196KD incorporates a built in Error Detection and Correction circuit for external memory reads and writes. The EDAC can be controlled from an external pin. The external pin (Pin 37) can be used to enable or disable this feature interactively. Therefore, different regions of external memory can be assigned to have EDAC as necessary. Additionally, the EDAC check bits will be passed through Port 0, which varies from the industry standard version where Port 0 is an input only port. You can control the interrupt behavior of the EDAC engine by setting bits 6 and 5 of the EDAC Control and Status Register (EDAC_CS). Additionally, reading bit 4 of the EDAC_CS allows you to determine if a double bit error occurred, and reading bits 3 through 0 of the EDAC_CS Register tells you how many single bit errors have been corrected. The EDAC_CS Register is located at location 15h of HWindow 1.

1.8 Instruction Queue

The instruction queue is eight bytes deep instead of four. The instruction queue also interfaces to the CPU through a 16-bit bus. This configuration will speed up the operation of the UT80C196KD.

1.9 WDT and Prescalar

The WDT can now be disabled through the software. The disable feature should allow the user flexibility in using the Watch Dog Timer. The WDT also now has a prescalar which can slow down the counter by a factor of 2^0 to 2^7 . The prescalar will give the user extra time between clears of the WDT. The WDT prescaler (WDT_SCALE) is located at location 0Dh of HWindow 1.

1.10 Interrupt Priority Levels

An additional level of priority encoding is available to the user. Every standard interrupt can be programed to a higher level of priority. All interrupts in the higher priority will maintain their relative priority, but low priority interrupts can then be programmed for a higher interrupt priority if necessary. The interrupt priority register is 16-bits wide, and maps to the standard interrupts in the same fashion as the INT_MASK and INT_MASK1 registers. The high byte of the Interrupt Priority Register (IN_PRI(hi)) is located at 0Bh of HWindow 1, and the low byte (INT_PRI(lo)) is located at 0Ah of HWindow 1.

1.11 Faster Multiply and Divide

The multiplier and divider have been optimized to perform their operations in fewer state times than in the current version.

1.12 Instructions State Time Reduction

The CPU has been streamlined for faster execution where possible. Examples include 1 state reduction for WORD immediate instructions, 1 state reductions for long indexed instructions, and state reductions for the BMOV instructions.

1.13 STACK_PNTR implemented as Special Function Register

The STACK_PNTR has been implemented as a true Special Function Register instead of in the RAM to allow for quicker pushes and pops. If the stack is not used, the SFR can be used for general purpose data storage.

1.14 Timer3

An additional 16-bit timer/counter has been implemented as a general purpose timer that can be used if Timer1 and Timer 2 are being dedicated to other functional uses. The current value

of Timer3 can be found in locations 0Fh (high byte), and 0Eh (low byte) of HWindow 1.

1.15 Input/Output Pullup/Pulldown Currents

Leakage currents may not meet the industry standard 80C196KD specs due to differently sized weak pullups/ pulldowns, during Quasi-Bidirectional and reset/powerdown modes. Refer to specs for I_{L11} and I_{L12} .

1.16 Power-down exit

Pin 37 will not be used to exit power-down mode. Since a digital clock is supplied, no connection between this V_{pp} pin and the power-down circuitry exists.

1.17 Test Mode Entry

Test mode entry will be via four pins: WR, \overline{RD} , ALE and \overline{HLDA} instead of PWM0.

1.18 Power-on Reset

The UT80C196KD will not guarantee the 16-state "pulse stretching" function of a Reset_n pulse applied at power-up. The user must hold Reset_n low until the power and clocks stabilize plus 16-state times, or provide a high to low transition after the power and clocks have stabilized.

1.19 Pullup/Pulldown states

The INST pin will be driven to a weak low during Reset. The ALE signal will be driven to a weak high during Bus Hold.

1.20 Modifying the INT_PEND registers

Two operand rd-modify-wr instructions should be used to modify the INT_PEND registers. Three operand rd-modify-wr instructions may lose an incoming interrupt.

1.21 Serial Port Synchronous Mode

The last clock rising edge to output float time (T_{XHQZ}) is made consistent with the output data hold (T_{XHQX}) time of 2 T_{OSC} +/-50nsec. This is longer than the industry standard of 1 T_{OSC} max.

1.22 Industry Standard Register Indirect with Auto Increment

The industry standard 80C196KD increments the auto-incremented register after determining the external address instead of at the end of the instruction completion. The UT80C196KD performs the auto-increment function at the end of the instruction processing. Please reference the example below that shows the processing difference between the UT80C196KD and the industry standard 80C196KD:

ST R0, [R0]+

assume R0 holds the value 1000h before the instruction is executed.

PROCESSING FLOW FOR THE ST R0, [R0]+ INSTRUCTION

in to the officity			
UT80C196KD	Industry Standard 80C196KD		
Address = [R0]; 1000h	Address = [R0]; 1000h		
R0> Address	R0 = R0+1; 1001h		
R0 = R0+1; 1001h	R0> Address		
* The contents in address 1000h are 1000h	* The contents in address 1000h are 1001h		

1.23 AC Timing Differences

There are some AC timing differences between the UT80C196KD and the industry standard 80C196KD. Most changes resulted in loosened timing specifications. However, the t_{RHDZ} and t_{RXDX} timing specifications were tightened by 5ns. If you have been designing to the industry standard 80C196KD timing specifications, it is important to recognize these two shortened timing specifications.

NOTE: Please visit the UTMC website at www.utmc.com to obtain the latest data sheet updates, application notes, software examples, advisories and erratas for the UT80C196KD.

1.24 T2UP-DN Input Signal

Port 2.6 has an alternate function of T2UP-DN enabled by IOC2.1. The industry standard device appears to allow writes into Port 2.6 to directly affect the pin state when in the T2UP-DN mode. (This would allow software control of the T2 direction, but requires ensuring a one (QBD pullup) is written to Port 2.6 if the pin is driven externally). The UT80C196KD device is designed to disable the Port 2.6 output when T2UP-DN is enabled. This protects the P2.6/T2UP-DN pin from contention with an externally driven signal, independent of the value written into Port 2.

1.25 NEG 8000h Instruction Operation

The UT80CRH196KD and the industry standard 80C196KD set the N-Flag differently when executing the NEG 8000h instruction. NEG represents the MCS-96 opcode to negate a defined operand (8000h). When the UT80CRH196KD executes the NEG 8000h instruction, the result becomes 8000h with both the N-Flag and the V-Flag set. The industry standard 80C196KD, however, executes the NEG 8000h instruction with a result of 8000h and only the V-Flag set.

1.26 Reserved Opcode EEH

The industry standard 80C196KD using the MCS-96 ISA declares the opcode EEH as a reserved opcode and does not guarantee the generation of the Unimplemented Opcode Interrupt. The UT80CRH196KD, on the other hand, generates the Unimplemented Opcode Interrupt when the EEH opcode is executed.

1.27 Byte-Wide Reads of the HSI_Time SFR

In order to ensure that the next HSI event is loaded from the FIFO into the HSI holding register, the HSI_TIME special function register must be read as a 16-bit word. Byte-wide reads of the HSI_TIME register will not result in successful loading of the HSI holding register.

1.28 BMOV and BMOVI Maximum Count Limitation

The BMOV and BMOVI instructions provide a powerful method to transferring a large block of data from one location in memory to another. The syntax for the BMOV and BMOVI instructions are as follows:

BMOV SRC_DEST_REG, CNTREG BMOVI SRC_DEST_REG, CNTREG

The SRC_DEST_REG is a long register that contains both addresses for the source and destination blocks. The CNTREG is a 16-bit register specifying the number of transfers being performed. Unlike the industry standard 80C196KD which will accept any 16-bit counter value, the UT80C196KD will only accept a value in the range of 0000H to 3FFFH.

1.29 BREQ Activation Prior to HLDA

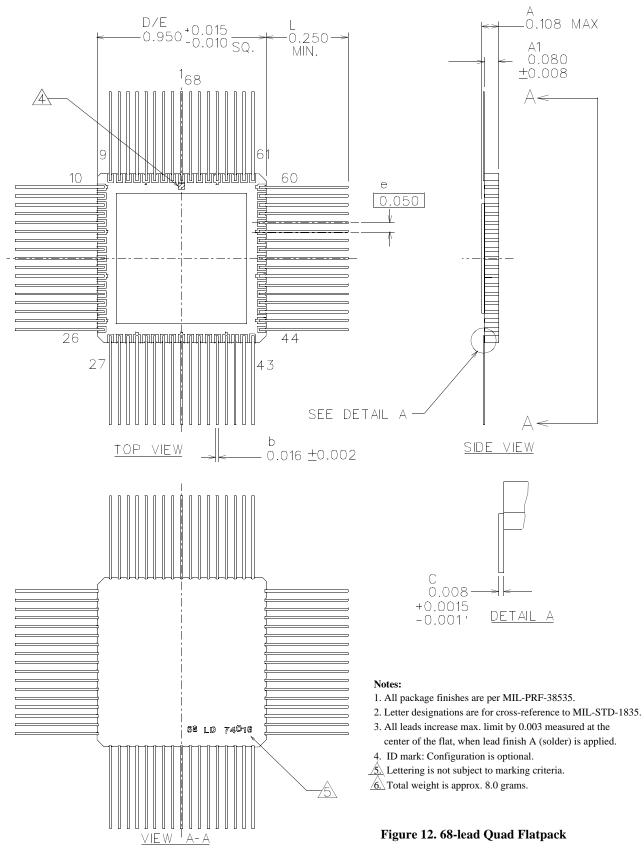
The BREQ signal is used by the UT80C196KD to signal a DMA arbiter that it would like to recover access to the memory bus. The UT80C196KD, on the other hand, uses the

HLDA signal to provide confirmation to the DMA arbiter that the UT80C196KD has relinquished control of the memory bus. If the wait state control signal (READY) is high when the UT80C196KD decides it will release the bus based on the assertion of the HOLD signal, it will drive the BREQ low one CLKOUT cycle ahead of its assertion of the HLDA. Conversely, if the READY signal is low when the UT80C196KD decides to relinquish the bus, it will assert BREQ coincidently with HLDA or some CLKOUT cycle later. The latter behavior is compatible with the industry standard 80C196KD functionality, but the former is unique to the UT80C196KD.

1.30 HOLD Must Be Synchronized with CLKOUT

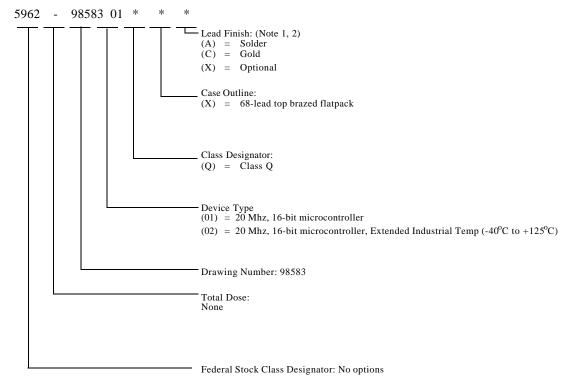
The DMA arbiter must synchronize the HOLD signal with the CLKOUT on the UT80C196KD. The timing diagram in Figure 8 eludes to the synchronicity of the HOLD signal, but does not clearly identify the outcome if the HOLD signal does not satisfy the timing parameter $t_{\rm HVCH}$. If the HOLD setup time is violated on the industry standard 80C196KD, it will require one additional CLKOUT cycle before it recognizes the state change of HOLD. Violating the HOLD setup time on the UT80C196KD will result in a metastable condition and the UT80C196KD's reaction is undefined.

8.0 PACKAGE



ORDERING INFORMATION



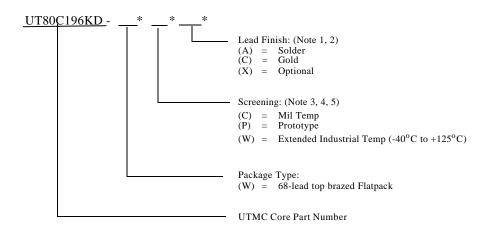


Notes:

1. Lead finish (A, C, or X) must be specified.

2. If an "X" is specified when ordering, part number will match the lead finish and will be either "A" (solder) or "C" (gold).

UT80C196KD Microcontroller



Notes:

- Notes:
 Lead finish (A,C, or X) must be specified.
 If an "X" is specified when ordering, then the part number will match the lead finish and will be either "A" (solder) or "C" (gold).
 Military Temperature Range flow per UTMC Manufacturing Flows Document. Devices are tested -55C, room temp, and 125C.
 Prototype flow per UTMC Manufacturing Flows Document Tested at 25C only. Lead finish is gold only.

- 5. Extended Industrial Temperature Range Flow per UTMC Manufacturing Flows Document. Devices are tested at -40°C, room temp, and +125°C. Radiation is neither tested nor guaranteed.

Notes